



Material Content Data Sheet



Sales Product Name				IPU50R1K4CE		Issued		25. September 2017	
MA#				MA001023782					
Package				PG-TO251-3-341		Weight*		380.95 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.378	0.36	0.36	3619	3619	
leadframe	inorganic material	phosphorus	7723-14-0	0.069	0.02		181		
	non noble metal	iron	7439-89-6	0.229	0.06		602		
	non noble metal	copper	7440-50-8	228.946	60.11	60.19	600992	601775	
	non noble metal	aluminium	7429-90-5	0.401	0.11	0.11	1053	1053	
wire	inorganic material	antimonytrioxide	1309-64-4	1.747	0.46		4585		
encapsulation	plastics	brominated resin	-	1.871	0.49		4913		
	organic material	carbon black	1333-86-4	1.996	0.52		5240		
	plastics	epoxy resin	-	16.843	4.42		44214		
	inorganic material	silicondioxide	60676-86-0	102.306	26.86	32.75	268557	327509	
leadfinish	non noble metal	tin	7440-31-5	3.740	0.98	0.98	9818	9818	
plating	non noble metal	nickel	7440-02-0	0.509	0.13	0.13	1336	1336	
solder	non noble metal	tin	7440-31-5	0.034	0.01		90		
	noble metal	silver	7440-22-4	0.043	0.01		112		
	non noble metal	lead	7439-92-1	1.631	0.43	0.45	4281	4483	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		15		
	non noble metal	iron	7439-89-6	0.019	0.00		50		
	non noble metal	copper	7440-50-8	19.177	5.03	5.03	50342	50407	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com